

RS78XX

1.0A Low Dropout Positive Voltage Regulator

General Description

The RS78XX series can provide local on-card regulation, eliminating the distribution problems associated with single point regulation. Each employs internal current limiting, thermal shut-down and safe operating area protection, making it essentially indestructible. If adequate heat sinking is provided, they can deliver over 1A output current. Although designed primarily as fixed voltage regulators, these devices can be used with external components to obtain adjustable voltages and currents.

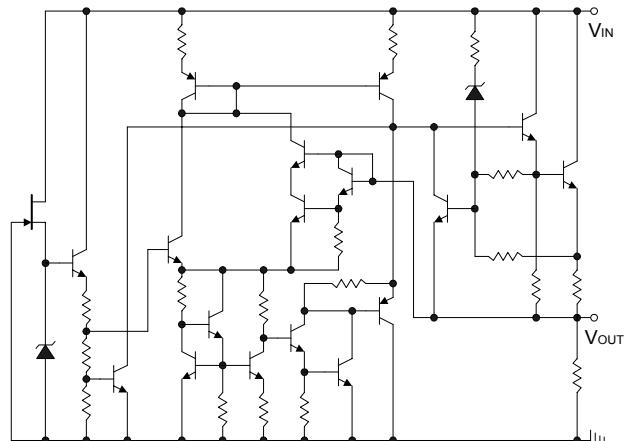
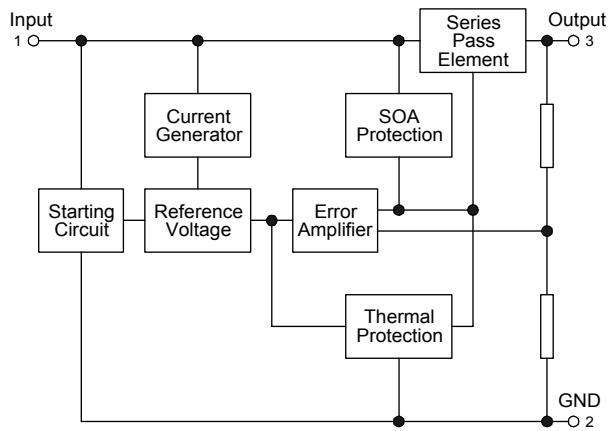
Features

- Output Current In Excess of 1A
- Output Voltages of 5V, 6V, 8V, 9V, 12V
- Internal Short-Circuit Current Limiting & Thermal Overload Protection
- Guaranteed In Extended Temperature Range

Applications

- SCSI-2 Active Termination
- High Efficiency Linear Regulators
- 5V to 3.3V Voltage Converter
- Battery Charger
- Battery Management Circuits For Notebook And Palmtop PCs
- Core Voltage Supply: FPGA, PLD, DSP, CPU

Schematic Diagram & Equivalent Circuit

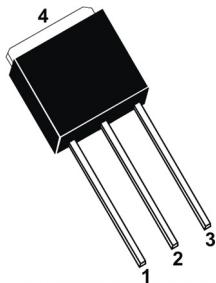
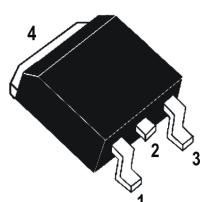
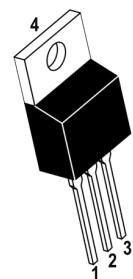


This integrated circuit can be damaged by ESD. Orister Corporation recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.



ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Pin Assignments

TO-251

TO-252

TO-220-3


PACKAGE	PIN	SYMBOL	DESCRIPTION
TO-251	1	VIN	Regulator Input Pin
	2, 4	GND	Ground Pin
	3	VOUT	Regulator Output Pin

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TO-252	1	VIN	Regulator Input Pin
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TO-220-3	1	VIN	Regulator Input Pin
	2, 4	GND	Ground Pin
	3	VOUT	Regulator Output Pin

Ordering Information

Part Number	V _{OUT}	Package
RS7805AJ	5V±0.15V	TO-252
RS7805AE	5V±0.15V	TO-220AB
RS7805AI	5V±0.15V	TO-251
RS7806AJ	6V±0.18V	TO-252
RS7806AE	6V±0.18V	TO-220AB
RS7806AI	6V±0.18V	TO-251
RS7808AJ	8V±0.24V	TO-252
RS7808AE	8V±0.24V	TO-220AB
RS7808AI	8V±0.24V	TO-251
RS7809AJ	9V±0.27V	TO-252
RS7809AE	9V±0.27V	TO-220AB
RS7809AI	9V±0.27V	TO-251
RS7812AJ	12V±0.36V	TO-252
RS7812AE	12V±0.36V	TO-220AB
RS7812AI	12V±0.36V	TO-251

Absolute Maximum Ratings

Parameter	Symbol	Maximum	Unit
Input Voltage	V _{IN}	40	V
Power Dissipation	P _D	Internally limited ^(Note)	W
Operating Temperature	T _{OPR}	0 to 125	°C
Storage Temperature	T _{STG}	-55 to 150	°C
Junction Temperature	T _J	150	°C

Note:

(1)T_A=25°C, TO-252 / TO-251: 1W, TO-220AB: 2.7W

(2)T_C=25°C, All package: 10W

Thermal Data

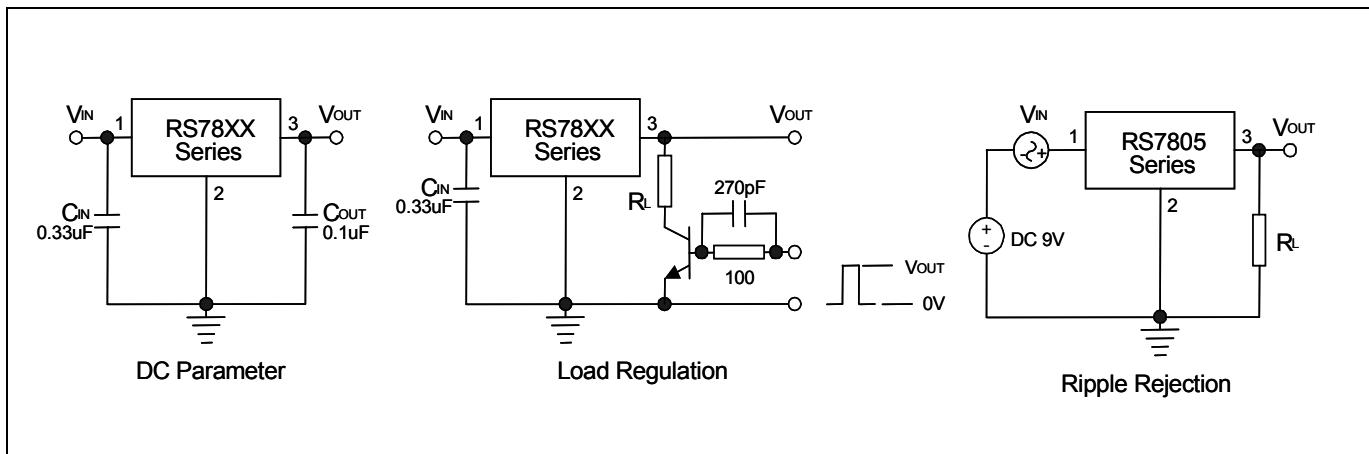
Characteristic	Symbol	TO-252 / TO-251	TO-220AB	Unit
Thermal Resistance Junction-Case	R _{th(j-c)}	12.5	12.5	°C/W
Thermal Resistance Junction-Ambient	R _{th(j-a)}	125	47	°C/W

RS7805A Series Electrical Characteristics

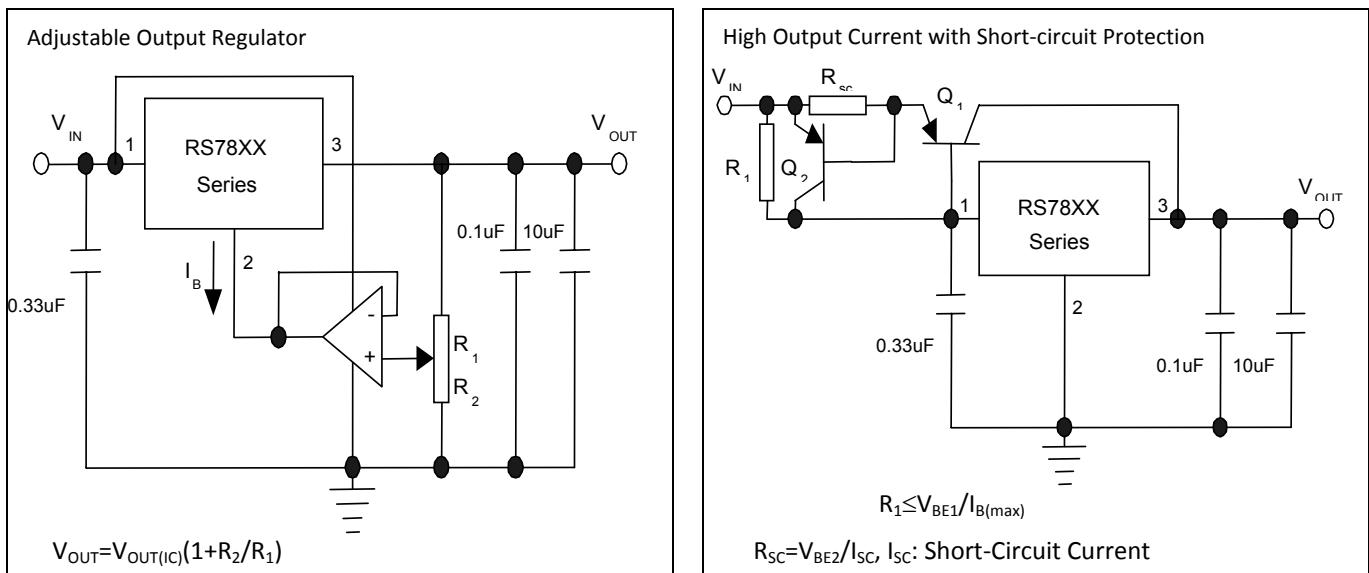
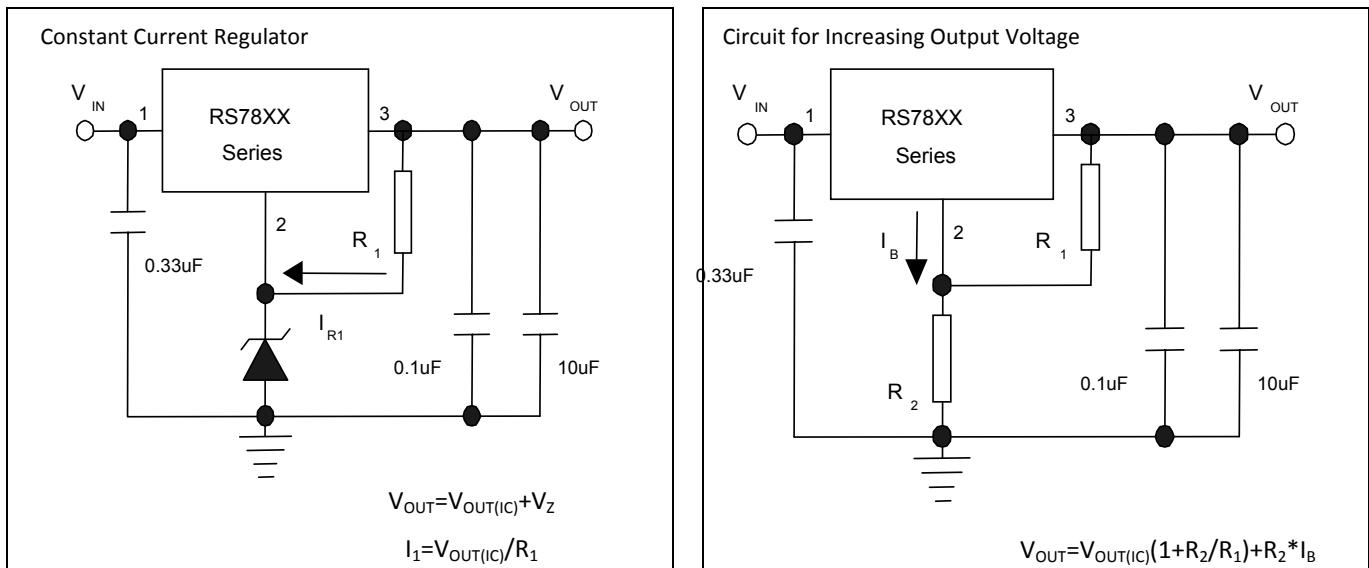
V_{IN}=10V, I_{OUT}=500mA, C_{IN}=0.33uF, C_{OUT}=0.1uF, 0°C≤T_J≤125°C (unless otherwise specified)

Symbol	Parameter	Conditions	RS7805AJ/E/I			Units	
			Min	Typ	Max		
V _O	Output Voltage	T _J =25°C, I _{OUT} =500mA	4.85	5	5.15	V	
		5mA≤I _{OUT} ≤1A	4.85	5	5.15		
		7V≤V _{IN} ≤25V, P _{OUT} ≤15W					
ΔV _O	Line Regulation	T _J =25°C, 7V≤V _{IN} ≤25V	-	3	50	mV	
		T _J =25°C, 8V≤V _{IN} ≤12V	-	1	25		
ΔV _O	Load Regulation	T _J =25°C, 5mA≤I _{OUT} ≤1A	-	15	100	mV	
		T _J =25°C, 250mA≤I _{OUT} ≤750mA	-	5	50		
I _B	Quiescent Current	I _{OUT} =5mA, T _J =25°C	-	3.9	8	mA	
ΔI _B	Quiescent Current Change	I _{OUT} =500mA, 7V≤V _{IN} ≤25V, T _J =25°C	-	-	1.3	mA	
		5mA≤I _{OUT} ≤1A, V _{IN} =10V, T _J =25°C	-	-	0.5		
eN	Output Noise Voltage	B=10Hz~100KHz, I _{OUT} =50mA, T _J =25°C	-	50	-	uV/V _O	
RR	Ripple Rejection	10V≤V _{IN} ≤18V, f=120Hz, I _{OUT} =50mA, T _J =25°C	57	73	-	dB	
V _D	Dropout Voltage	T _J =25°C, I _{OUT} =1A	-	2	2.5	V	
R _O	Output Resistance	f=1KHz	-	17	-	mΩ	
I _{SC}	Short Circuit Current	T _J =25°C	-	2.3	2.8	A	
ΔV _O /ΔT	Output Voltage Drift	0°C≤T _J ≤125°C	-	-	0.6	mV/°C	

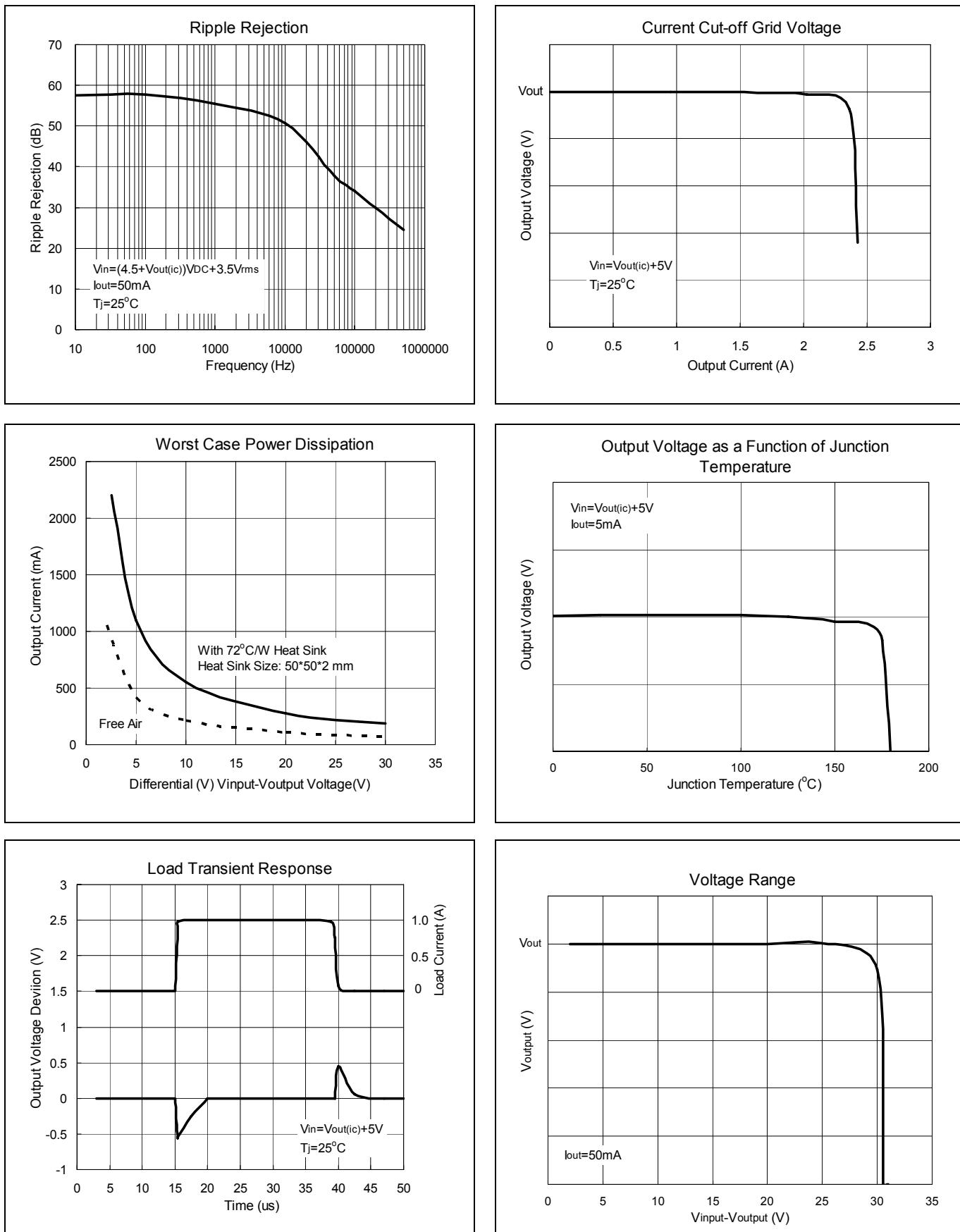
Test Circuits



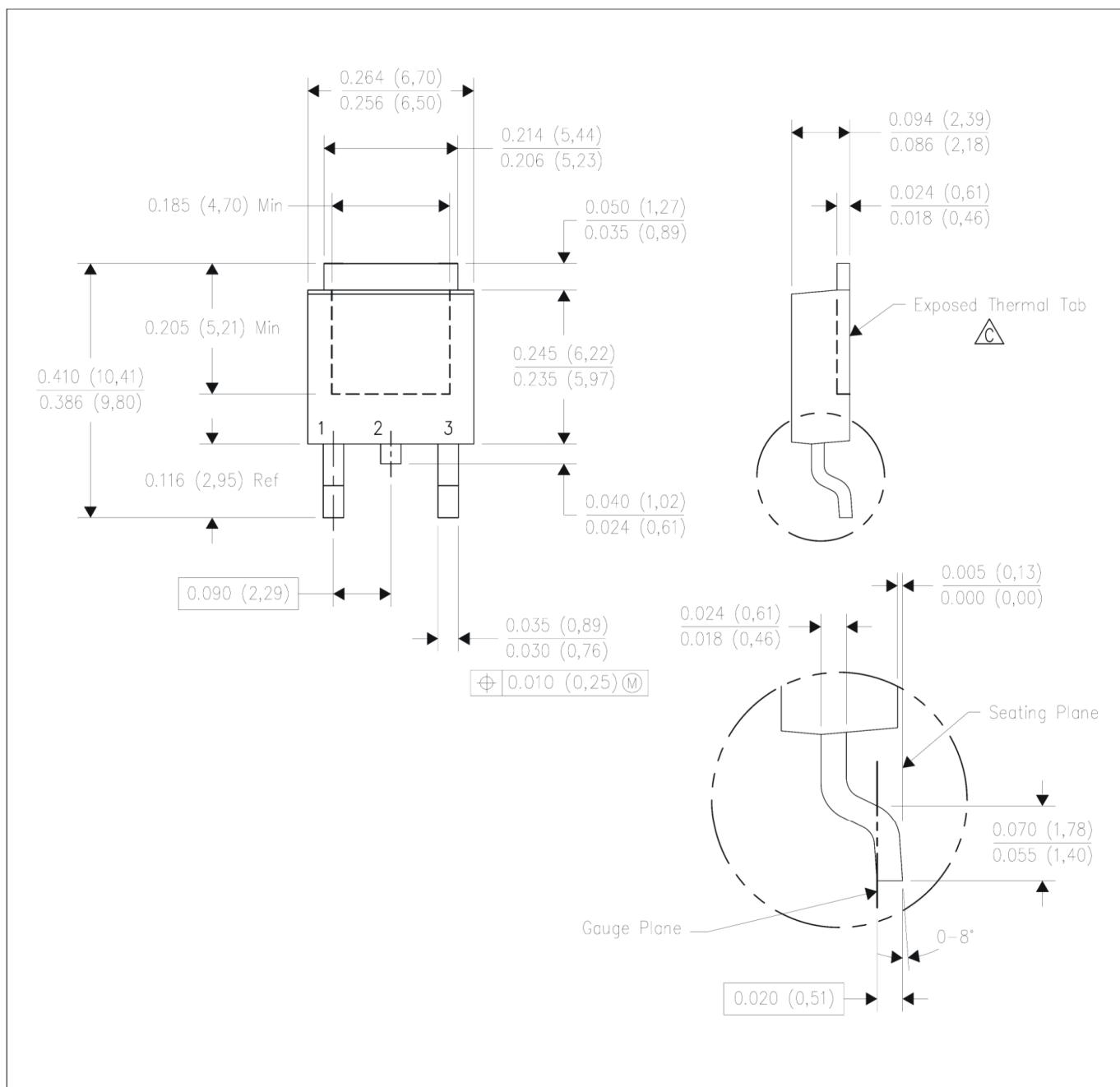
Application Circuits



Characteristics Curve



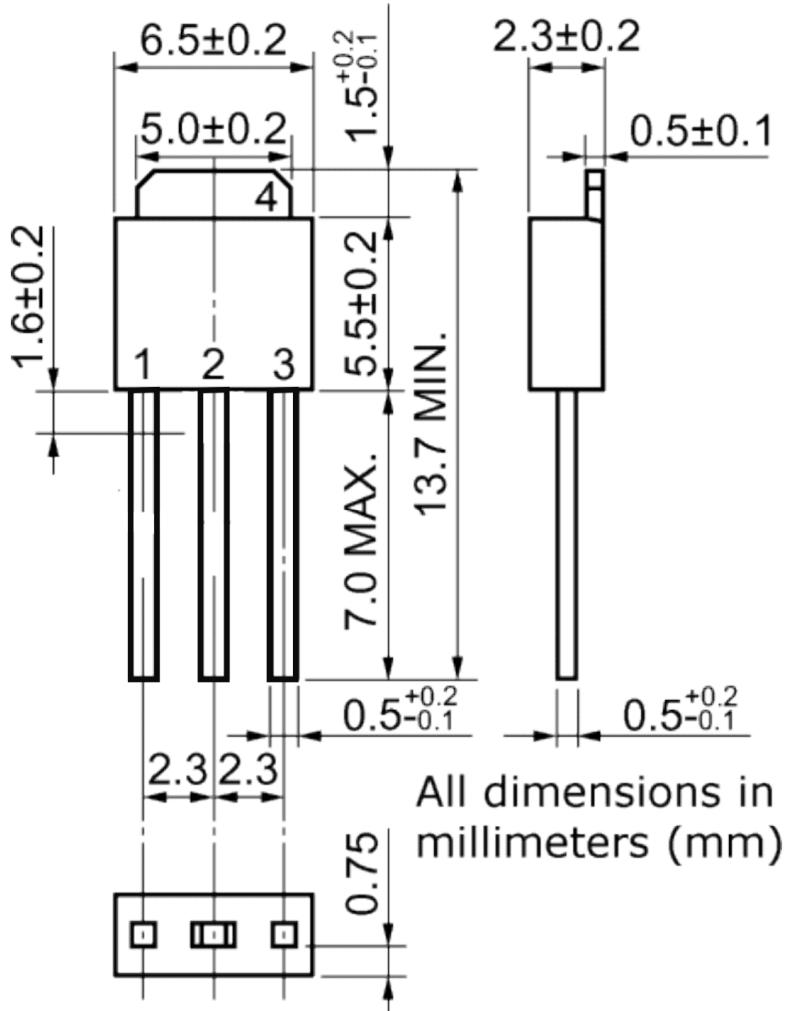
TO-252 Dimension



NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- The center lead is in electrical contact with the tab.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC TO-252 variation AA.

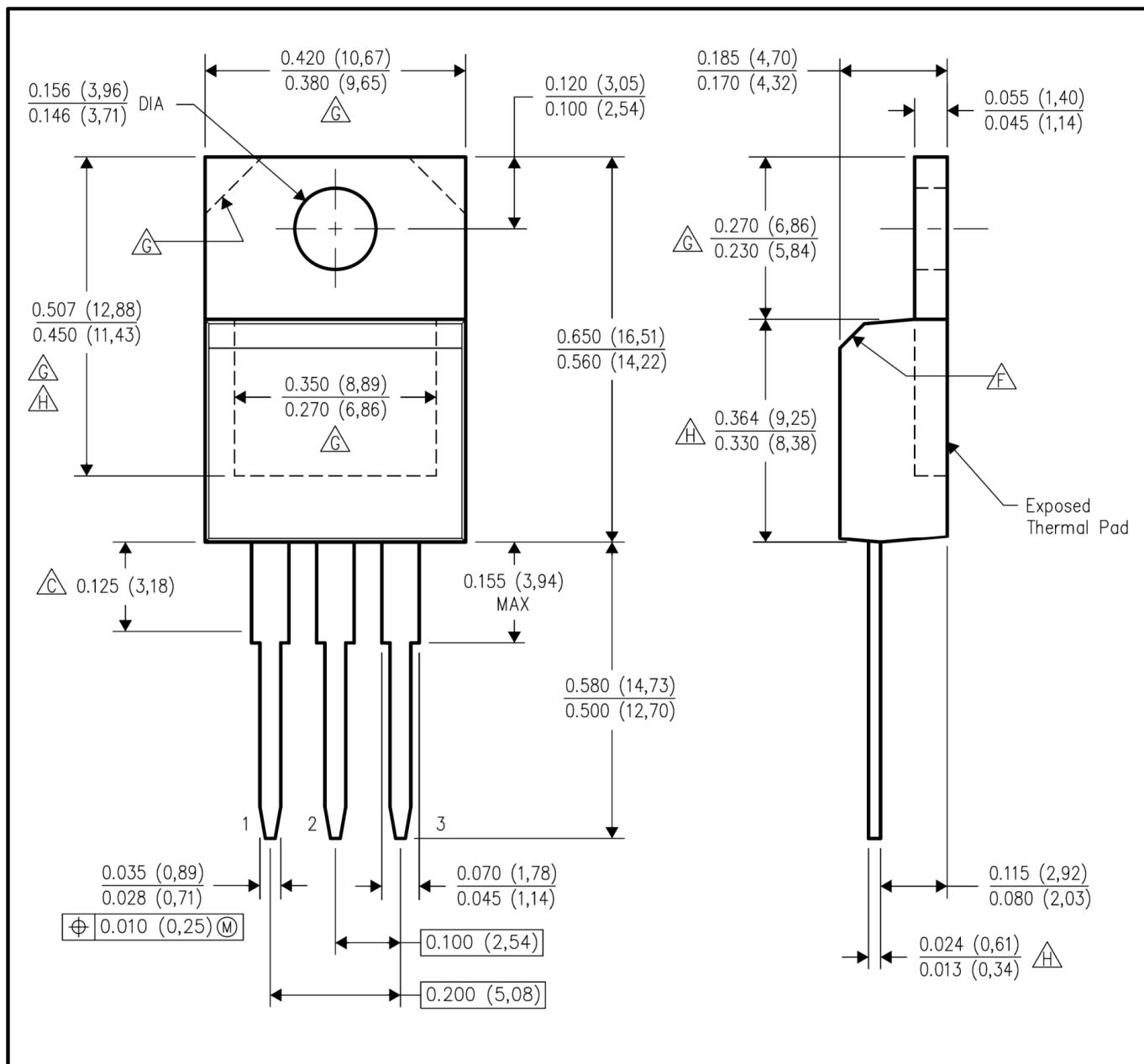
TO-251 Dimension



NOTES:

- G. All linear dimensions are in inches (millimeters).
- H. This drawing is subject to change without notice.
- I. The center lead is in electrical contact with the tab.
- J. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- K. Thermal pad contour optional within these dimensions.
- L. Falls within JEDEC TO-251 variation AA.

TO-220-3 Dimension



NOTES:

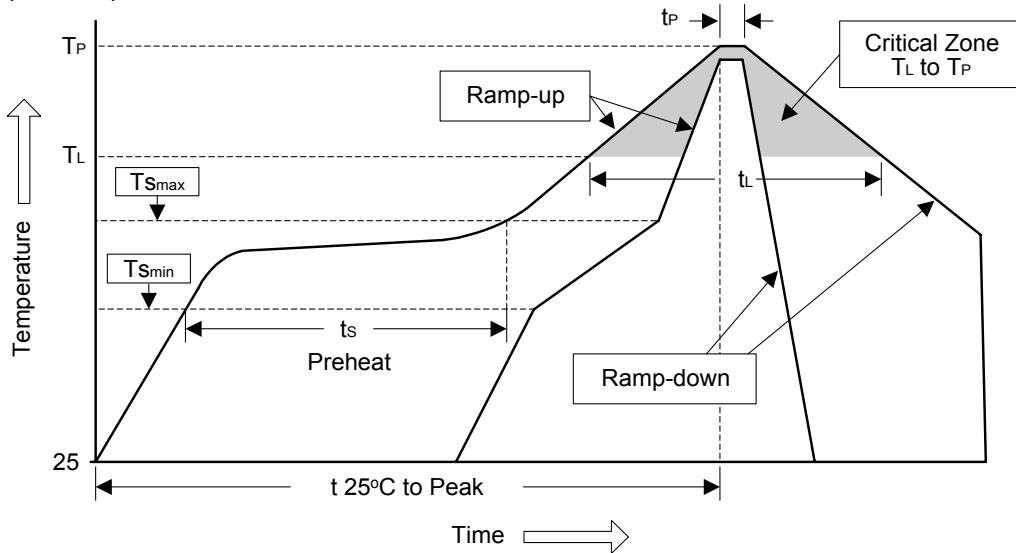
- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- All lead dimensions apply before solder dip.
- The center lead is in electrical contact with the tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC TO-220 variation AB. Except minimum lead thickness, minimum exposed pad length, and maximum body length.

Soldering Methods for Orister's Products

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%

2. Reflow soldering of surface-mount devices

Figure 1: Temperature profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	<3°C/sec	<3°C/sec
Preheat		
- Temperature Min ($T_{S\min}$)	100°C	150°C
- Temperature Max ($T_{S\max}$)	150°C	200°C
- Time (min to max) (t_s)	60~120 sec	60~180 sec
$T_{S\max}$ to T_L		
- Ramp-up Rate	<3°C/sec	<3°C/sec
Time maintained above:		
- Temperature (T_L)	183°C	217°C
- Time (t_L)	60~150 sec	60~150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_p)	10~30 sec	20~40 sec
Ramp-down Rate	<6°C/sec	<6°C/sec
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak temperature	Dipping time
Pb devices.	245°C ±5°C	5sec ±1sec
Pb-Free devices.	260°C +0/-5°C	5sec ±1sec

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